

Title (en)

METHOD AND SYSTEM OF CLEANING A WAFER AFTER CHEMICAL MECHANICAL POLISHING OR PLASMA PROCESSING

Title (de)

VERFAHREN UND SYSTEM ZUR REINIGUNG EINES WAFERS NACH CHEMISCH- MECHANISCHEM POLIEREN ODER PLASMABEHANDLUNG

Title (fr)

PROCEDE ET SYSTEME DE NETTOYAGE DE PLAQUETTE APRES UN POLISSAGE MECANICO-CHIMIQUE OU UN TRAITEMENT AU PLASMA

Publication

EP 1190441 A1 20020327 (EN)

Application

EP 00943063 A 20000623

Priority

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- US 34467199 A 19990625

Abstract (en)

[origin: US6405399B1] A method and system are provided for cleaning a surface of a semiconductor wafer following a fabrication operation. The system includes a brush box, which has a fluid manifold and at least one nozzle. The nozzle is connected to the fluid manifold by a flexible conduit. The nozzle is configured to spray a liquid onto the surface of the wafer at an application angle and at a fan angle. The application angle is defined between a plane of the surface of the wafer and a spraying plane of the liquid. The fan angle and the application angle are configured such that the spraying liquid covers the surface of the wafer in a quiescent manner.

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IPC 8 full level

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CPC (source: EP KR US)

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